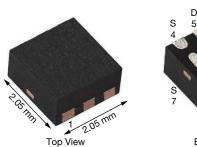
www.vishay.com

Vishay Siliconix

Automotive N-Channel 30 V (D-S) 175 °C MOSFET

PowerPAK® SC-70-6L Single





Marking Code: QHXXXX

PRODUCT SUMMARY									
V _{DS} (V)	30								
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.056								
$R_{DS(on)}(\Omega)$ at $V_{GS} = 2.5 \text{ V}$	0.070								
I _D (A)	2.25								
Configuration	Single								
Package	PowerPAK SC-70								

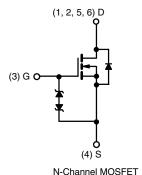
FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified
- 100 % Rq and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE



ABSOLUTE MAXIMUM RATING	GS (T _C = 25 °C, unless	s otherwise noted)			
PARAMETER		SYMBOL	LIMIT	UNIT		
Drain-source voltage		V _{DS}	30			
Gate-source voltage		V _{GS}	± 12	V		
Continuous drain current a	T _C = 25 °C	1	2.25			
Continuous drain current a	T _C = 125 °C	I _D	2.25			
Continuous source current (diode conducti	on) ^a	I _S	2.25	Α		
Pulsed drain current ^a		I _{DM}	9			
Single pulse avalanche current	J 0.1 ml J	I _{AS}	9			
Single pulse avalanche energy L = 0.1 ml		E _{AS}	4	mJ		
Maximum power dissipation ^b	T _C = 25 °C	D	13.6	W		
maximum power dissipation •	T _C = 125 °C	P_{D}	4.5	VV		
Operating junction and storage temperature	e range	T _J , T _{stg}	-55 to +175	°C		
Soldering recommendations (peak tempera	ature) ^{d, e}		260	C		

THERMAL RESISTANCE RATINGS									
PARAMETER		SYMBOL	LIMIT	UNIT					
Junction-to-ambient	PCB mount c	R_{thJA}	90	°C/W					
Junction-to-case (drain)		R_{thJC}	11	C/VV					

Notes

- a. Package limited
- b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %
- c. When mounted on 1" square PCB (FR4 material)
- d. See solder profile (www.vishay.com/doc?73257). The PowerPAK SC-70 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components



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PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT		
Static	•	•			·	•		
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		30	-	-	V	
Gate-source threshold voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	0.6	1	1.6	V	
Cata aguirea laglicara		V _{DS} =	-	-	± 100	nA		
Gate-source leakage	I _{GSS}	V _{DS} =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 15		
		$V_{GS} = 0 V$	V _{DS} = 30 V	-	-	1	١ .	
Zero gate voltage drain current	I _{DSS}	V _{GS} = 0 V	V _{DS} = 30 V, T _J = 125 °C	-	-	50	- μA -	
		V _{GS} = 0 V	V _{DS} = 30 V, T _J = 175 °C	-	-	250		
On-state drain current a	I _{D(on)}	V _{GS} = 4.5 V	$V_{DS} \ge 5 \text{ V}$	10	-	-	Α	
		V _{GS} = 4.5 V	I _D = 2 A	-	0.038	0.056		
Drain-source on-state resistance a	В	V _{GS} = 4.5 V	I _D = 2 A, T _J = 125 °C	-	-	0.084		
Dialii-Source oii-state resistance "	R _{DS(on)}	V _{GS} = 4.5 V	I _D = 2 A, T _J = 175 °C	-	-	0.099	Ω	
		V _{GS} = 2.5 V	I _D = 2 A	-	0.044	0.070]	
Forward transconductance b	9 _{fs}	V _{DS} = 15 V, I _D = 3 A		-	13	-	S	
Dynamic ^b								
Input capacitance	C _{iss}			-	362	453		
Output capacitance	C _{oss}	$V_{GS} = 0 V$	V _{GS} = 0 V V _{DS} = 20 V, f = 1 MHz		66	83	pF	
Reverse transfer capacitance	C _{rss}			-	38	48	1	
Total gate charge ^c	Qg			-	4.1	5.2		
Gate-source charge ^c	Q_{gs}	$V_{GS} = 4.5 \text{ V}$	$V_{DS} = 15 \text{ V}, I_D = 4.2 \text{ A}$	-	0.58	-	nC	
Gate-drain charge c	Q _{gd}	7			1.1	-	1	
Gate resistance	R_g	f = 1 MHz		1.9	3.2	5.1	Ω	
Turn-on delay time ^c	t _{d(on)}			-	8.2	10.3		
Rise time ^c	t _r	V_{DD} = 10 V, R_L = 10 Ω		-	22	28	ns	
Turn-off delay time ^c	t _{d(off)}	I _D ≅ 1 A, \	-	21	26			
Fall time ^c	t _f		-	26	32			
Source-Drain Diode Ratings and Char	racteristics ^b							
Pulsed current ^a	I _{SM}			-		9	Α	
Forward voltage	V_{SD}	I _F =	4.5 A, V _{GS} = 0 V	-	0.75	1.2	V	
		•				•		

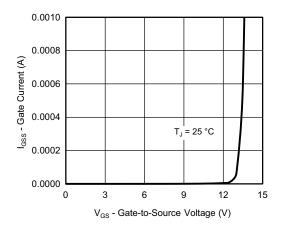
Notes

- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing
- c. Independent of operating temperature

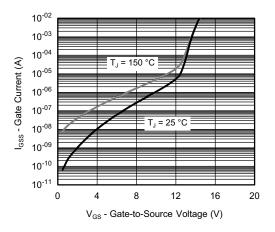
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



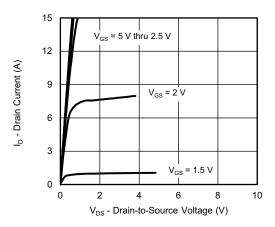
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



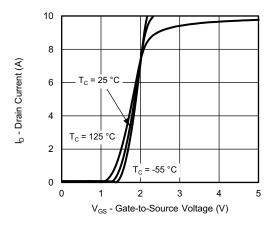
Gate Current vs. Gate-Source Voltage



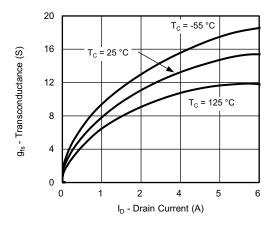
Gate Current vs. Gate-Source Voltage



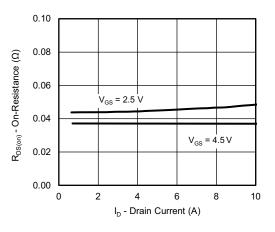
Output Characteristics



Transfer Characteristics



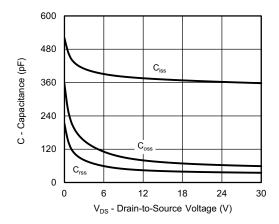
Transconductance



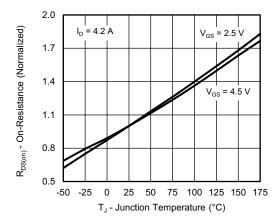
On-Resistance vs. Drain Current



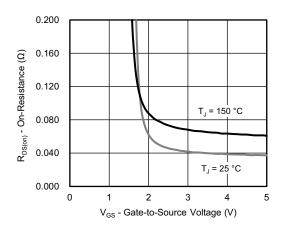
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



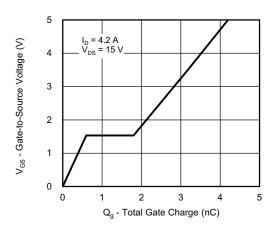
Capacitance



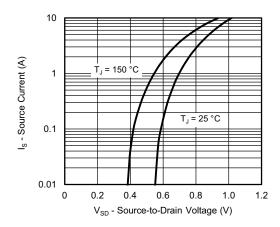
On-Resistance vs. Junction Temperature



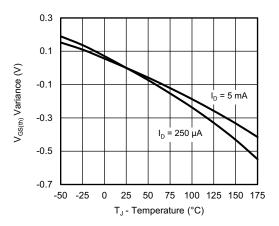
On-Resistance vs. Gate-to-Source Voltage



Gate Charge



Source Drain Diode Forward Voltage

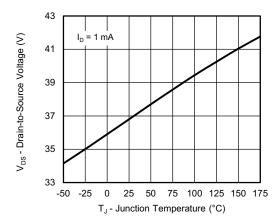


Threshold Voltage

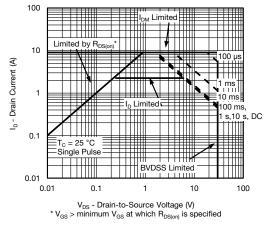
For technical questions, contact: automos.techsupport@



TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

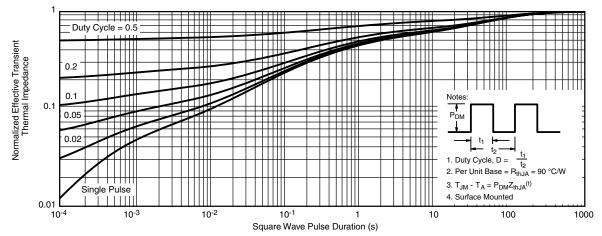


Drain Source Breakdown vs. Junction Temperature



Safe Operating Area

THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)

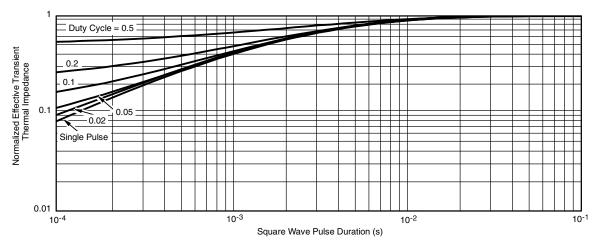


Normalized Thermal Transient Impedance, Junction-to-Ambient

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THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions

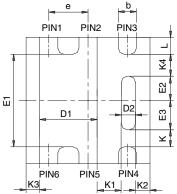
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?76236.

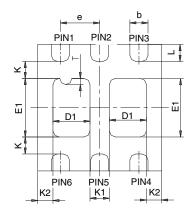




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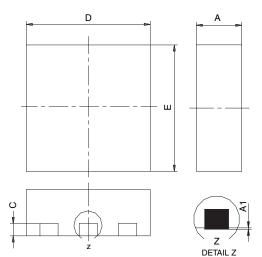
PowerPAK® SC70-6L





BACKSIDE VIEW OF SINGLE

BACKSIDE VIEW OF DUAL



- All dimensions are in millimeters
 Package outline exclusive of mold flash and metal burr
 Package outline inclusive of plating

	SINGLE PAD						DUAL PAD						
DIM	M	ILLIMETER	RS		INCHES		М	ILLIMETER	RS		INCHES		
	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	
Α	0.675	0.75	0.80	0.027	0.030	0.032	0.675	0.75	0.80	0.027	0.030	0.032	
A 1	0	-	0.05	0	-	0.002	0	-	0.05	0	-	0.002	
b	0.23	0.30	0.38	0.009	0.012	0.015	0.23	0.30	0.38	0.009	0.012	0.015	
С	0.15	0.20	0.25	0.006	0.008	0.010	0.15	0.20	0.25	0.006	0.008	0.010	
D	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085	
D1	0.85	0.95	1.05	0.033	0.037	0.041	0.513	0.613	0.713	0.020	0.024	0.028	
D2	0.135	0.235	0.335	0.005	0.009	0.013							
Е	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085	
E1	1.40	1.50	1.60	0.055	0.059	0.063	0.85	0.95	1.05	0.033	0.037	0.041	
E2	0.345	0.395	0.445	0.014	0.016	0.018							
E3	0.425	0.475	0.525	0.017	0.019	0.021							
е		0.65 BSC			0.026 BSC	;	0.65 BSC			0.026 BSC			
K		0.275 TYP			0.011 TYP	1	0.275 TYP			0.011 TYP			
K1		0.400 TYP			0.016 TYP			0.320 TYP			0.013 TYP		
K2		0.240 TYP		0.009 TYP		0.252 TYP		0.010 TYP					
К3		0.225 TYP		0.009 TYP									
K4		0.355 TYP			0.014 TYP								
L	0.175	0.275	0.375	0.007	0.011	0.015	0.175	0.275	0.375	0.007	0.011	0.015	
Т							0.05	0.10	0.15	0.002	0.004	0.006	
ECN: C O	07/21 Pay C 06 Aug 07												

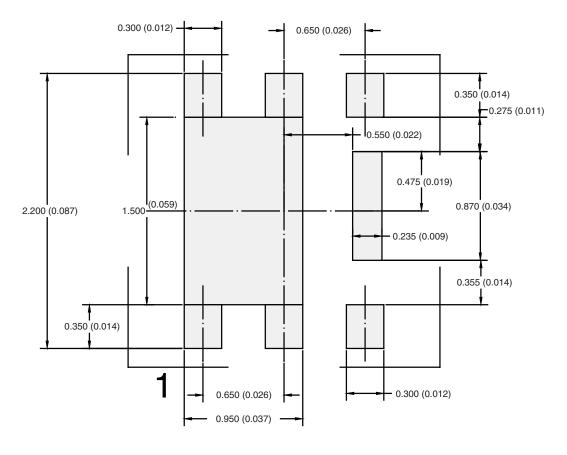
ECN: C-07431 - Rev. C, 06-Aug-07

DWG: 5934

Document Number: 73001 06-Aug-07



RECOMMENDED PAD LAYOUT FOR PowerPAK® SC70-6L Single



Dimensions in mm/(Inches)

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